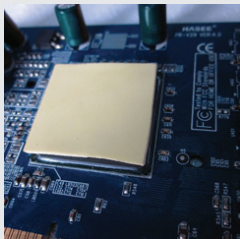


Technical Data Sheet

EVSF500G CPU led thermal pads are used for filling the two contact surfaces. They are ultra soft and have good resilience, so effectively exclude air from the contact interface. The products are naturally tacky, can be die-cut into various shapes, easy to operate. The thermal conductivity can reach 3.5 w/m-k.



Material Properties

- High thermal conductivity
- Excellent flame retardant
- Good electrical insulation performance
- Good flexibility and high compression ratio

Applications

- ✓ Semiconductor heat sink
- ✓ Electric Vehicle (EV) Batteries
- ✓ Communication & power devices & modules
- ✓ LED lighting equipment
- ✓ Electronic components like: LEDs, CPUs, MOS • Mobiles, Laptops, Tablets



EVSF500G

Color	Pink	Visual
Thickness	0.3 ~ 10.0mm	ASTM D374
Specific Gravity	3.0g/cc	ASTM D792
Thermal Conductivity	3.50 W/m-K	ASTM D5470
Hardness (shore oo)	30-90	ASTM D2240
Elongation	30%	ASTM D412
Tensile Strength	30psi	ASTM D412
Electrical Strength	>8000V/mm	ASTM D149
UL Flammability Rating	UL94 V-0	
Volume resistivity	2*10 ¹³ Ω.cm	ASTM D257
Operating Temperature	-50 ~ 200	---
Thermal Resistance(1mm,@40psi)	0.35 *in ² /W	ASTM D5470
Compression Ratio(1mm,@40psi)	35%	---
Dielectric Constant MHz	7.8	ASTM D150
RoHS	PASS	IEC 62321
Halogen	PASS	EN14582
REACH	PASS	EN143

Test fixtures using ASTM D5470. Recorded values include interface thermal resistance. These values are for reference only. The actual application performance is directly related to the applied surface roughness, flatness and pressure.

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Note: The information provided herein is accurate at time of publication. It is the responsibility of the end-user to confirm compliance to their application. All test data is typical. Therefore, these recommendations and data are for reference only and not as a product warranty.